

Title (en)

METHOD FOR METALLISATION OF A SEMICONDUCTOR DEVICE

Title (de)

VERFAHREN ZUR METALLISIERUNG EINES HALBLEITERBAUELEMENTS

Title (fr)

PROCEDE DE METALLISATION D'UN DISPOSITIF SEMI-CONDUCTEUR

Publication

**EP 1854148 A1 20071114 (FR)**

Application

**EP 06709407 A 20060118**

Priority

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Abstract (en)

[origin: WO2006077342A1] The invention relates to a method for metallisation of a semiconductor device (100). Said method comprises the following steps: a) metallisation of a set of collector fingers (8.1 to 8.n) with a screen printing paste called low temperature on at least one face (17), called the front face of the semiconductor device (100), b) carrying out a sintering, of the screen printing paste forming the set of metallised collector fingers (8.1 to 8.n) at a temperature below that which damages the semiconductor device (100), by means of pressing said collector fingers (8.1 to 8.n) with a press (10), c) metallisation of at least one collector bus (16a, 16b) for the set of metallised collector fingers (8.1 à 8.n), which electrically connects said collector fingers to each other (8.1 to 8.n) using a screen printing paste called low temperature .

IPC 8 full level

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